

Specification for an SMT – Gullwing Oscillator MtronPTI P/N: M2002S992

I. GENERAL & ELECTRICAL REQUIREMENTS:

II.

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Frequency of Operation	Fo		14.745600		MHz	
]	Frequency Sta	bilities		
Initial Frequency Tolerance		-25		+25	ppm	@ 23°C ±3°C
	ΔF/F	-100		+100	ppm	Includes initial tolerance, deviation
Frequency Stability						over temperature, shock, vibration,
						voltage & load variations, and aging
			Output			
Output Type		HCMO	S/TTL Compat	ible		
Output Load				15	pF	
Symmetry (duty cycle)	T_{DC}	40		60	%	@ 50% of waveform
Logic "1" Level	V_{OH}	$90\% V_{DD}$			V	HCMOS load
Logic "0" Level	V_{OL}			10%	V	HCMOS load
Logic o Level				V_{DD}		
Rise/Fall Time	T_R/T_F			10	nsec	From 10% to 90% V _{CC}
		Ac	lditional Speci	fications		
Start-up Time	T_{SU}			10	msec	
Enable/Disable Time				150	nS	
Enable/Disable Function	Enable	Logic High. or N/C			V	Pad 1: Output Enabled
	Disable]	Logic Low.			Pad 1: Output is high-Z when disabled
		Su	pply and Tem	perature		
Operating Voltage	V_{CC}	2.97	3.3	3.63	V_{DC}	
Operating Current	I_{CC}			15	mА	
Operating Temperature	OTR	-55		+125	$^{\circ}C$	

II. ENVIRONMENTAL/MECHANICAL REQUIREMENTS:

II. EN VIKONVIEN I AL/ME	CHANICAL REQUIREMENTS:	
Mechanical Shock	Per MIL-STD-202, Method 213, Condition C (100 g's, 6 mS duration, ½ Sinewave)	
Vibration	Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)	
Thermal Cycle	Per MIL-STD-883, Method 1010, B (-55°C to 125°C, 15 min. dwell, 10 cycles)	
Storage Temperature	-55°C to +125°C	
Hermeticity	MIL-STD-883, Method 1014, Test Condition A1 for Fine Leak, Test Condition C1 for Gross	
	Leak	
Solderability	Per MIL-STD-883, Method 2003	
Max. Soldering Conditions	See solder profile, Figure 1	
Package Type	4 - Pad leadless ceramic package with (4) Gullwing Leads attached (M2 Type)	
Reflow Conditions	+260°C for 10 seconds. Max (See Section V)	
Lead Attachment	Thermo-compression Weld using Copper Leads and Gold Pads	
Lead Pull Test	Shall withstand 8oz. pull per MIL-STD-883, Method 2004, Condition A	
Lead Finish	Hot Solder Dipped, Sn63Pb37 alloy or equivalent	



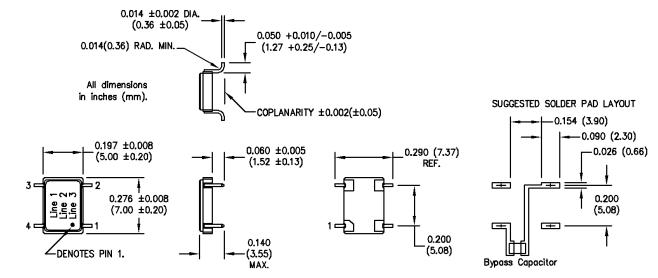
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IV. Mechanical, Marking and Layout Information:

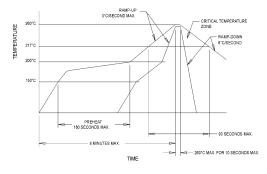
Pad	Function
1	Tristate
2	Ground
3	Output
4	+V _{CC}

Part Marking		
Line 1	M2002S992	
Line 2	14M7456	
Line 3	M yyww	

Legend		
уу	Year	
ww	Work week	



V. SOLDER PROFILE:



DATA SHEET REVISION TABLE:

Date	Rev.	Author	Details of Revision
04/08/13	4	BRM	Updated the datasheet with a revised outline drawing.
10/04/12	3	BRM	Updated the package drawing at the customer's request to include then package body width and overall height dimensions.
9/14/12	2	BRM	Updated the package drawing for greater dimensional detail
9/7/12	1	BRM	Original release.